

Product description

- Thermal conductive, flame retardant
- 1:1 two-part addition-type potting silicone rubber

Product features

- High thermal conductivity and flowability
- Both room temperature and heat curing
- Good weather and aging resistance
- Excellent insulation properties
- Flame retardant UL94V-0
- Maintains rubber elasticity from -50°C to 200°C
- RoHS Directive

Typical applications

- All kinds of electrical components of thermal conductivity, flame retardant potting, such as photovoltaic inverters, LED drive power, charging piles, automotive electronics, NEV power and controllers etc.

Directions for use

Preparation: Fully stir part A and part B respectively by manual or mechanical, to avoid change of performance caused by filler settlement.

Mixing: Accurately weigh the two parts into a clean container by weight ratio and stir well.

Defoaming: Natural defoaming: 20-30min should be left after filling the mixed glue into the components.

Vacuum defoaming: Pot the components after pumping for 5-10min at a vacuum degree of 0.08-0.1MPa.

Potting: The surfaces on which the adhesive has to be applied should be clean and dry. The components should be potted when the glue still has good flowability, otherwise the leveling will be affected.

Curing: The glue is curable at room temperature or by heating. Curing will be accelerated with rising temperature, and heat curing is recommended in winter.

Storage condition

Store at 0-35°C in a cool and dry place.

Shelf life is 12 months.

Technical parameters

Reference standard ¹	Item	Unit	Value
Physical properties before curing (25±2°C, 60%±5%RH)			
Q/HTXC 2	Appearance (A)	--	Grey fluid
	Appearance (B)	--	White fluid
GB/T2794	Viscosity (A)	mPa·s	3500~5500
	Viscosity (B)	mPa·s	2800~4800
GB/T13354	Density (A)	g/cm ³	1.91±0.05
	Density (B)	g/cm ³	1.95±0.05
Physical properties after curing (25±2°C, 60±5%RH, A:B=1:1)			
Q/HTXC 2	Operating time	min	60~180
Q/HTXC 2	Gel time (25°C)	h	3~5
Q/HTXC 2	Gel time (80°C)	min	≤30
GB/T 531	Hardness (ShoreA)	--	30~40
Q/HTXC 2	Dielectric strength	KV/mm	≥18
Q/HTXC 2	Volume resistivity	Ω·cm	≥1.0×10 ¹⁴
ISO 22007-2	Thermal conductivity	W/m·K	0.9~1.0

Note 1: The reference standards are not dated and their latest versions are applicable to this document.

Cautions

Store the product in a sealed container, and keep away from children for storage.

The glue will not cure if exposed to a certain amount of the following chemicals:

Organic compounds of N, P and S, ionic compounds of Sn, Pb, Hg, As, etc.;

Compounds containing alkyne and polyvinyl.

To avoid the above problem, Any residual rosin on the circuit board should be wiped clean when using the glue, and use soldering tin with low lead content.

This product is non-hazardous. Please consult the MSDS of the product for safety information.

Packing specification

Order code:

5296 A6 25 kg/barrel, 5296R A6 10kg/ barrel

5296 B6 25 kg/barrel, 5296R B6 10kg/barrel